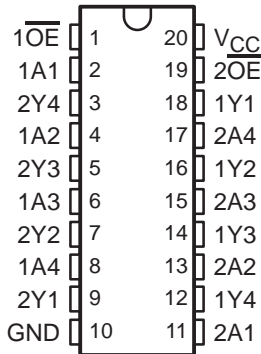


SN54LVTH240, SN74LVTH240 3.3-V ABT OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

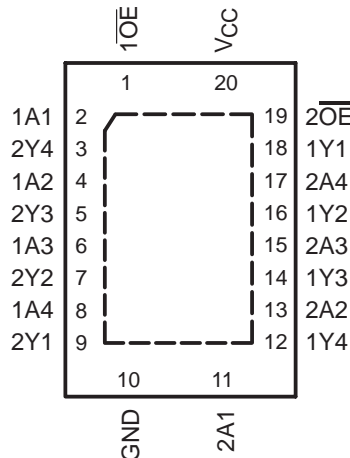
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- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce) <0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- I_{off} and Power-Up 3-State Support Hot Insertion
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

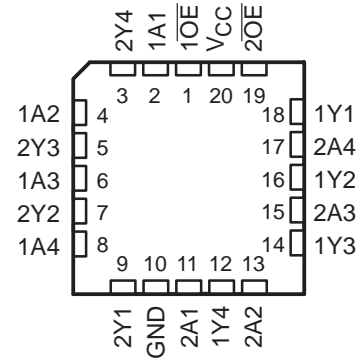
SN54LVTH240 . . . J OR W PACKAGE
SN74LVTH240 . . . DB, DW, NS,
OR PW PACKAGE
(TOP VIEW)



SN74LVTH240 . . . RGY PACKAGE
(TOP VIEW)



SN54LVTH240 . . . FK PACKAGE
(TOP VIEW)



description/ordering information

These octal buffers and line drivers are designed specifically for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	QFN – RGY	Tape and reel	SN74LVTH240RGYR	LXH240
	SOIC – DW	Tube	SN74LVTH240DW	LVTH240
		Tape and reel	SN74LVTH240DWR	
	SOP – NS	Tape and reel	SN74LVTH240NSR	LVTH240
	SSOP – DB	Tape and reel	SN74LVTH240DBR	LXH240
	TSSOP – PW	Tube	SN74LVTH240PW	LXH240
		Tape and reel	SN74LVTH240PWR	
VFBGA – GQN	Tape and reel	SN74LVTH240GQNR	LXH240	
		SN74LVTH240ZQNR		
-55°C to 125°C	CDIP – J	Tube	SNJ54LVTH240J	SNJ54LVTH240J
	CFP – W	Tube	SNJ54LVTH240W	SNJ54LVTH240W
	LCCC – FK	Tube	SNJ54LVTH240FK	SNJ54LVTH240FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

SN54LVTH240, SN74LVTH240

3.3-V ABT OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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description/ordering information (continued)

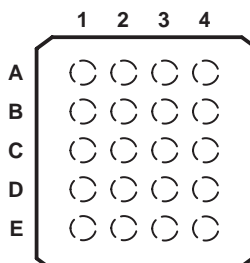
These devices are organized as two 4-bit buffer/line drivers with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the devices pass data from the A inputs to the Y outputs. When \overline{OE} is high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

SN74LVTH240 . . . GQN OR ZQN PACKAGE (TOP VIEW)



terminal assignments

	1	2	3	4
A	1A1	$\overline{1OE}$	V_{CC}	$\overline{2OE}$
B	1A2	2A4	2Y4	1Y1
C	1A3	2Y3	2A3	1Y2
D	1A4	2A2	2Y2	1Y3
E	GND	2Y1	2A1	1Y4

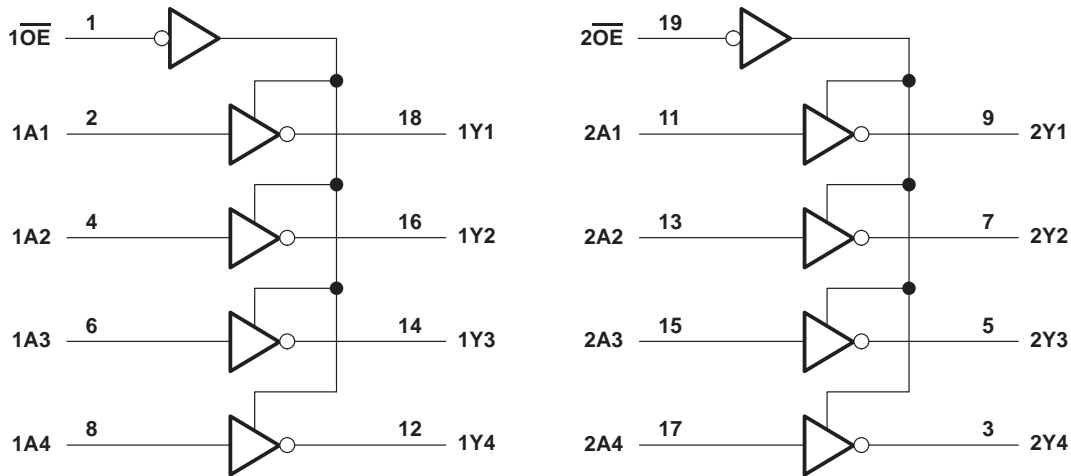
FUNCTION TABLE (each 4-bit buffer)

INPUTS		OUTPUT Y
\overline{OE}	A	
L	H	L
L	L	H
H	X	Z

SN54LVTH240, SN74LVTH240 3.3-V ABT OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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logic diagram (positive logic)



Pin numbers shown are for the DB, DW, FK, J, NS, PW, RGY, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	-0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	-0.5 V to 7 V
Voltage range applied to any output in the high-impedance or power-off state, V_O (see Note 1)	-0.5 V to 7 V
Voltage range applied to any output in the high state, V_O (see Note 1)	-0.5 V to $V_{CC} + 0.5$ V
Current into any output in the low state, I_O : SN54LVTH240	96 mA
SN74LVTH240	128 mA
Current into any output in the high state, I_O (see Note 2): SN54LVTH240	48 mA
SN74LVTH240	64 mA
Input clamp current, I_{IK} ($V_I < 0$)	-50 mA
Output clamp current, I_{OK} ($V_O < 0$)	-50 mA
Package thermal impedance, θ_{JA} (see Note 3): DB package	70°C/W
(see Note 3): DW package	58°C/W
(see Note 3): GQN/ZQN package	78°C/W
(see Note 3): NS package	60°C/W
(see Note 3): PW package	83°C/W
(see Note 4): RGY package	37°C/W
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
 3. The package thermal impedance is calculated in accordance with JESD 51-7.
 4. The package thermal impedance is calculated in accordance with JESD 51-5.

SN54LVTH240, SN74LVTH240
3.3-V ABT OCTAL BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS

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recommended operating conditions (see Note 5)

		SN54LVTH240		SN74LVTH240		UNIT
		MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage	2.7	3.6	2.7	3.6	V
V _{IH}	High-level input voltage	2		2		V
V _{IL}	Low-level input voltage		0.8		0.8	V
V _I	Input voltage		5.5		5.5	V
I _{OH}	High-level output current		-24		-32	mA
I _{OL}	Low-level output current		48		64	mA
Δt/Δv	Input transition rise or fall rate	Outputs enabled		10	10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate	200		200		μs/V
T _A	Operating free-air temperature	-55	125	-40	85	°C

NOTE 5: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



SN54LVTH240, SN74LVTH240
3.3-V ABT OCTAL BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54LVTH240			SN74LVTH240			UNIT	
				MIN	TYP†	MAX	MIN	TYP†	MAX		
V_{IK}		$V_{CC} = 2.7\text{ V}$, $I_I = -18\text{ mA}$		-1.2			-1.2			V	
V_{OH}		$V_{CC} = 2.7\text{ V to }3.6\text{ V}$, $I_{OH} = -100\text{ }\mu\text{A}$		$V_{CC}-0.2$			$V_{CC}-0.2$			V	
		$V_{CC} = 2.7\text{ V}$, $I_{OH} = -8\text{ mA}$		2.4			2.4				
		$V_{CC} = 3\text{ V}$		2			2				
V_{OL}		$V_{CC} = 2.7\text{ V}$		$I_{OL} = 100\text{ }\mu\text{A}$		0.2			0.2		
				$I_{OL} = 24\text{ mA}$		0.5			0.5		
		$V_{CC} = 3\text{ V}$		$I_{OL} = 16\text{ mA}$		0.4			0.4		
				$I_{OL} = 32\text{ mA}$		0.5			0.5		
				$I_{OL} = 48\text{ mA}$		0.55			0.55		
				$I_{OL} = 64\text{ mA}$		0.55			0.55		
I_I		Control inputs $V_{CC} = 0\text{ or }3.6\text{ V}$, $V_I = 5.5\text{ V}$ $V_{CC} = 3.6\text{ V}$, $V_I = V_{CC}\text{ or GND}$		10			10			μA	
				± 1			± 1				
Data inputs		$V_{CC} = 3.6\text{ V}$		$V_I = V_{CC}$		1			1		
				$V_I = 0$		-5			-5		
I_{off}		$V_{CC} = 0$, $V_I\text{ or }V_O = 0\text{ to }4.5\text{ V}$					± 100			μA	
$I_I(\text{hold})$		$V_{CC} = 3\text{ V}$		$V_I = 0.8\text{ V}$		75			75		
				$V_I = 2\text{ V}$		-75			-75		
		$V_{CC} = 3.6\text{ V}\ddagger$, $V_I = 0\text{ to }3.6\text{ V}$					500 -750			μA	
I_{OZH}		$V_{CC} = 3.6\text{ V}$, $V_O = 3\text{ V}$		5			5			μA	
I_{OZL}		$V_{CC} = 3.6\text{ V}$, $V_O = 0.5\text{ V}$		-5			-5			μA	
I_{OZPU}		$V_{CC} = 0\text{ to }1.5\text{ V}$, $V_O = 0.5\text{ V to }3\text{ V}$, $OE = \text{don't care}$		$\pm 100^*$			± 100			μA	
I_{OZPD}		$V_{CC} = 1.5\text{ V to }0$, $V_O = 0.5\text{ V to }3\text{ V}$, $OE = \text{don't care}$		$\pm 100^*$			± 100			μA	
I_{CC}		$V_{CC} = 3.6\text{ V}$, $I_O = 0$, $V_I = V_{CC}\text{ or GND}$		Outputs high		0.19			0.19		
				Outputs low		5			5		
				Outputs disabled		0.19			0.19		
$\Delta I_{CC}\S$		$V_{CC} = 3\text{ V to }3.6\text{ V}$, One input at $V_{CC} - 0.6\text{ V}$, Other inputs at $V_{CC}\text{ or GND}$		0.2			0.2			mA	
C_i		$V_I = 3\text{ V or }0$		3			3			pF	
C_o		$V_O = 3\text{ V or }0$		7			7			pF	

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

† All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

§ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.



SN54LVTH240, SN74LVTH240
3.3-V ABT OCTAL BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS

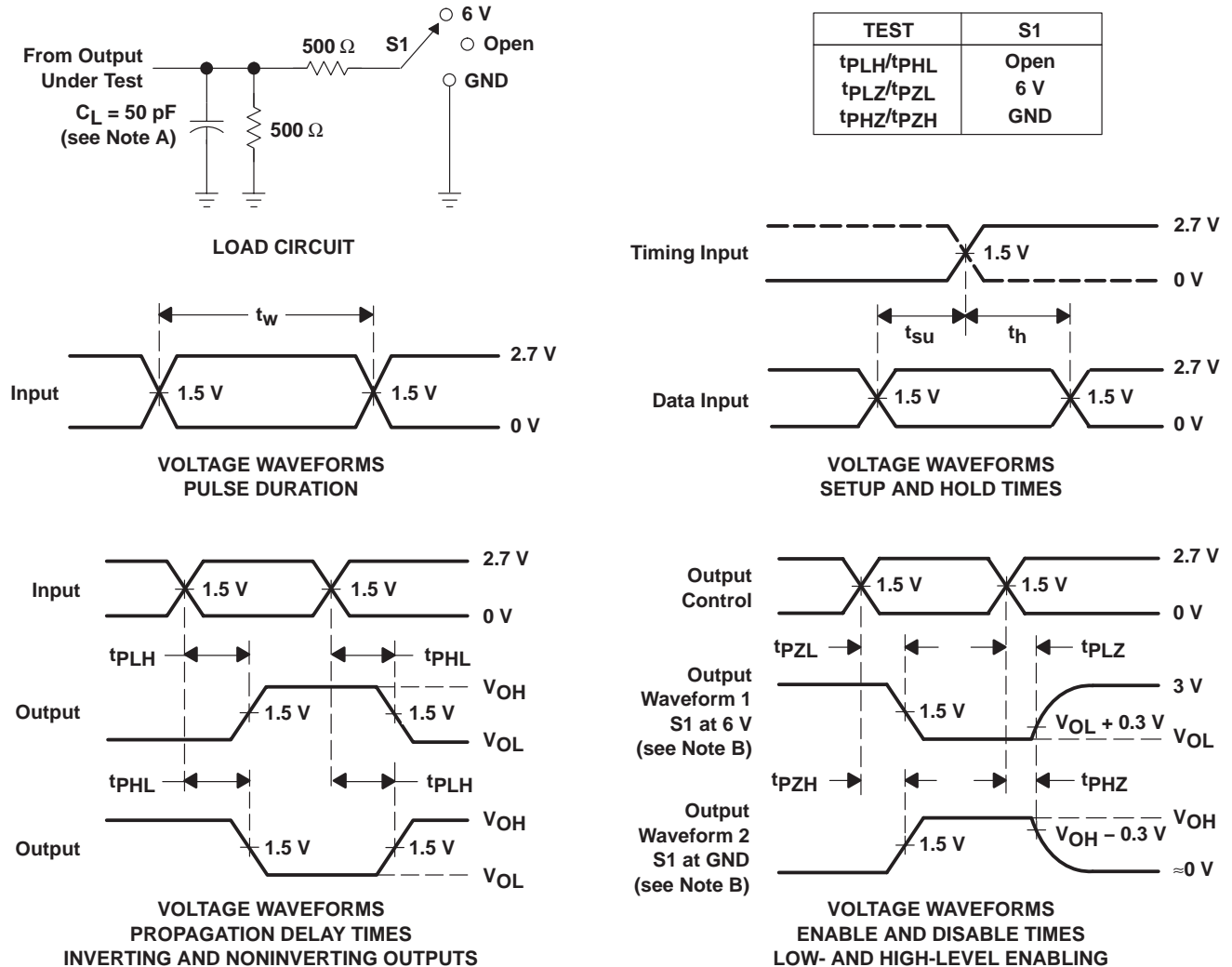
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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54LVTH240				SN74LVTH240				UNIT	
			$V_{CC} = 3.3 V \pm 0.3 V$		$V_{CC} = 2.7 V$		$V_{CC} = 3.3 V \pm 0.3 V$			$V_{CC} = 2.7 V$		
			MIN	MAX	MIN	MAX	MIN	TYP†	MAX	MIN		MAX
tPLH	A	Y	0.9	4.3	5.1		1.1	2.2	3.8	4.6		ns
tPHL			1.2	4.7	4.9		1.3	2.6	4	4.2		
tPZH	\overline{OE}	Y	1	5.7	6.7		1.1	2.6	4.6	5.6		ns
tPZL			1.2	5.5	6.2		1.4	2.7	4.4	5		
tPHZ	\overline{OE}	Y	1	5.1	5.2		2	2.9	4.4	4.6		ns
tPLZ			1.1	5.4	5.4		1.8	3	4.3	4.3		

† All typical values are at $V_{CC} = 3.3 V$, $T_A = 25^\circ C$.

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 D. The outputs are measured one at a time with one transition per measurement.
 E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9950801Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9950801QRA	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
5962-9950801QSA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type
5962-9950801V2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9950801VRA	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SN74LVTH240DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI
SN74LVTH240DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH240DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH240DBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH240DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH240DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH240DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH240DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH240DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH240DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH240GQNR	NRND	BGA MICROSTAR JUNIOR	GQN	20	1000	TBD	SNPB	Level-1-240C-UNLIM
SN74LVTH240NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH240NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH240NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH240PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH240PWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH240PWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH240PWLE	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI
SN74LVTH240PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH240PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH240PWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH240RGYR	ACTIVE	QFN	RGY	20	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LVTH240RGYRG4	ACTIVE	QFN	RGY	20	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN74LVTH240ZQNR	ACTIVE	BGA MI CROSTA R JUNI OR	ZQN	20	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM
SNJ54LVTH240FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LVTH240J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LVTH240W	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN54LVTH240, SN54LVTH240-SP, SN74LVTH240 :

- Enhanced Product: [SN74LVTH240-EP](#)

NOTE: Qualified Version Definitions:

- Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVTH240DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74LVTH240DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74LVTH240GQNR	BGA MICROSTAR JUNIOR	GQN	20	1000	330.0	12.4	3.3	4.3	1.6	8.0	12.0	Q1
SN74LVTH240GQNR	BGA MICROSTAR JUNIOR	GQN	20	1000	330.0	12.4	3.3	4.3	1.5	8.0	12.0	Q1
SN74LVTH240NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74LVTH240PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
SN74LVTH240RGYR	QFN	RGY	20	1000	180.0	12.4	3.8	4.8	1.6	8.0	12.0	Q1
SN74LVTH240ZQNR	BGA MICROSTAR JUNIOR	ZQN	20	1000	330.0	12.4	3.3	4.3	1.5	8.0	12.0	Q1
SN74LVTH240ZQNR	BGA MICROSTAR JUNIOR	ZQN	20	1000	330.0	12.4	3.3	4.3	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVTH240DBR	SSOP	DB	20	2000	346.0	346.0	33.0
SN74LVTH240DWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74LVTH240GQNR	BGA MICROSTAR JUNIOR	GQN	20	1000	340.5	338.1	20.6
SN74LVTH240GQNR	BGA MICROSTAR JUNIOR	GQN	20	1000	346.0	346.0	29.0
SN74LVTH240NSR	SO	NS	20	2000	346.0	346.0	41.0
SN74LVTH240PWR	TSSOP	PW	20	2000	346.0	346.0	33.0
SN74LVTH240RGYR	QFN	RGY	20	1000	190.5	212.7	31.8
SN74LVTH240ZQNR	BGA MICROSTAR JUNIOR	ZQN	20	1000	346.0	346.0	29.0
SN74LVTH240ZQNR	BGA MICROSTAR JUNIOR	ZQN	20	1000	340.5	338.1	20.6

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

GQN (R-PBGA-N20)

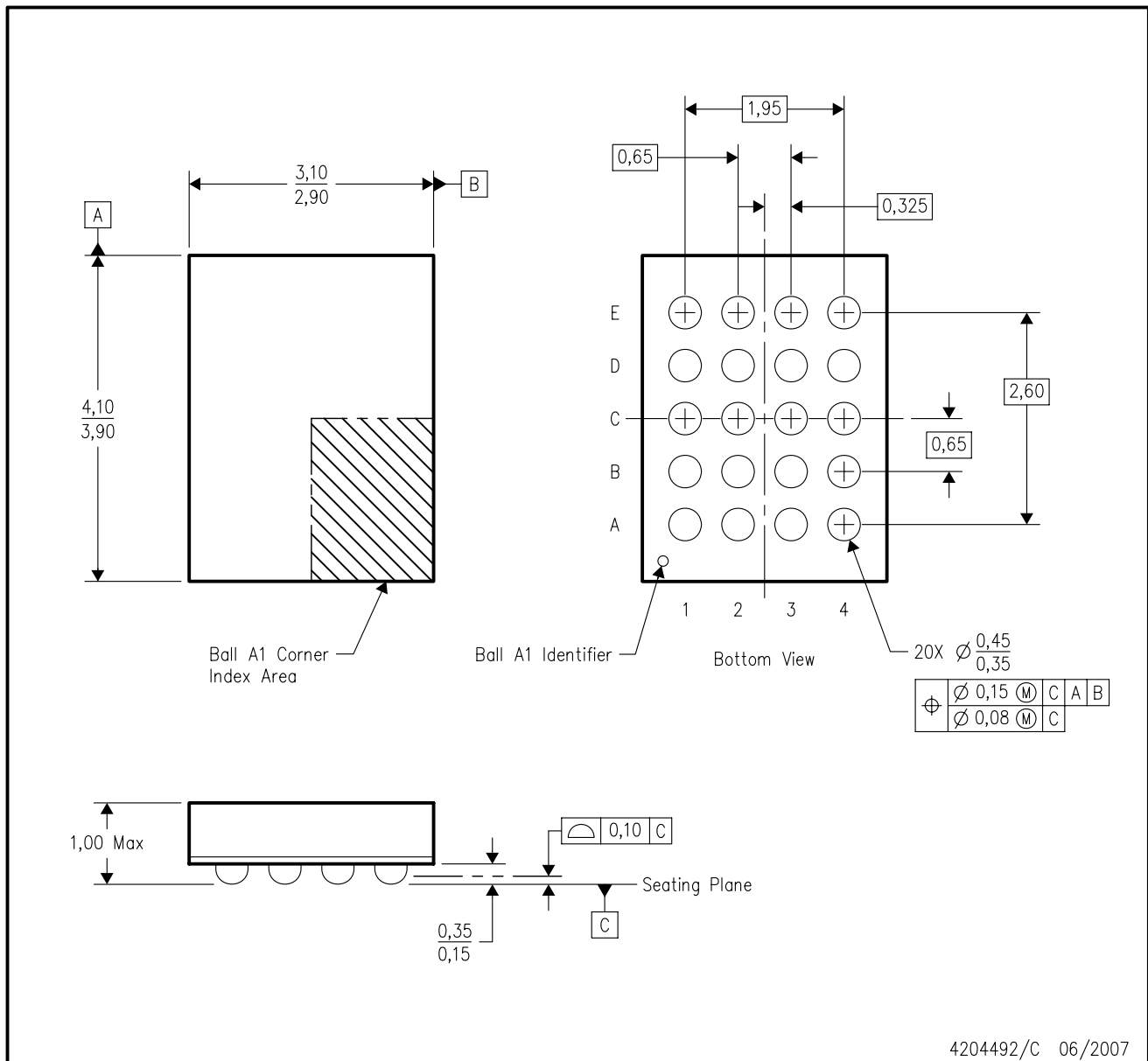
PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MO-285 variation BC-2.
 - D. This package is tin-lead (SnPb). Refer to the 20 ZQN package (drawing 4204492) for lead-free.

ZQN (R-PBGA-N20)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MO-285 variation BC-2.
 - D. This package is lead-free. Refer to the 20 GQN package (drawing 4200704) for tin-lead (SnPb).

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

W (R-GDFP-F20)

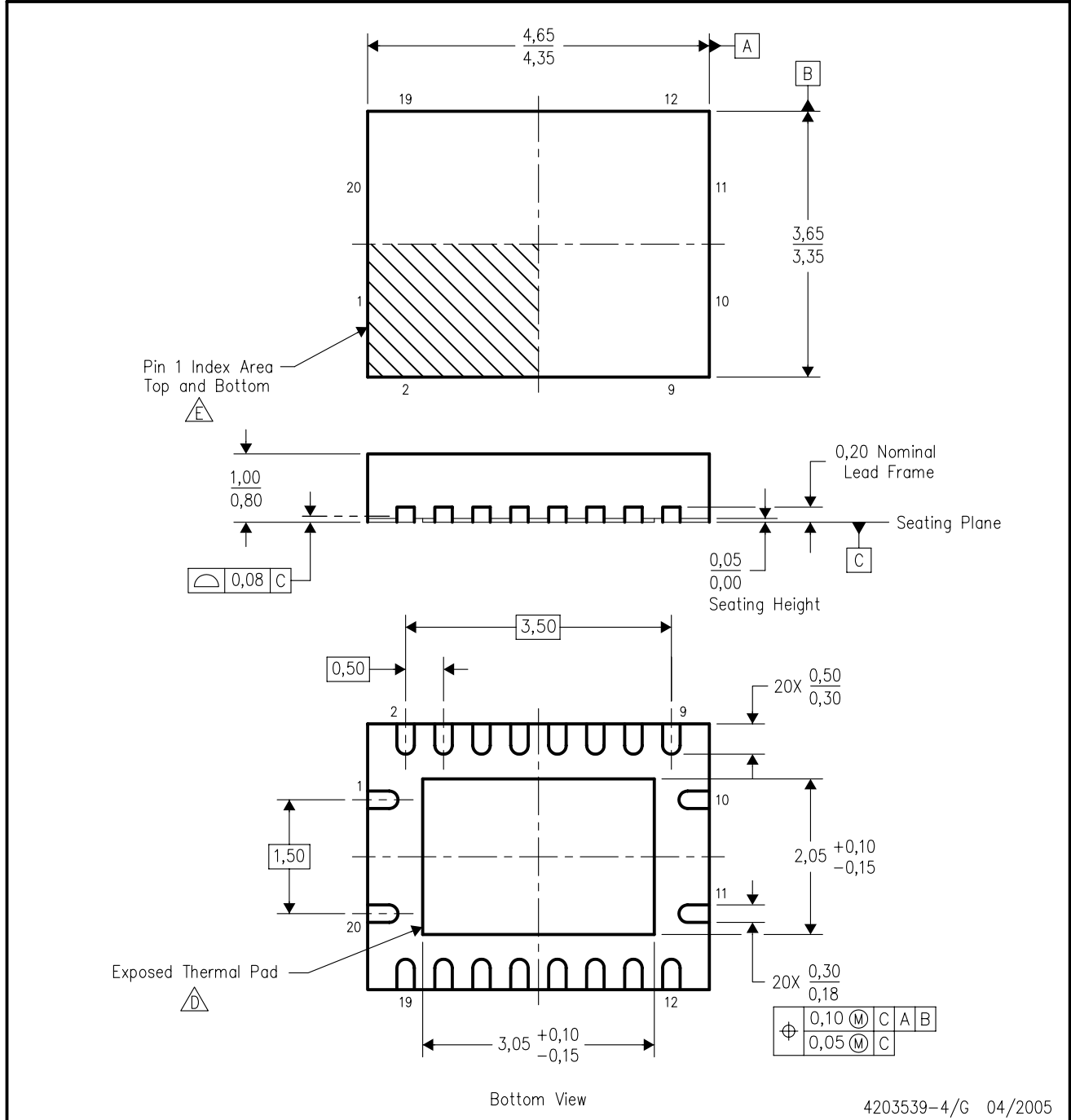
CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within Mil-Std 1835 GDFP2-F20

RGY (R-PQFP-N20)

PLASTIC QUAD FLATPACK



4203539-4/G 04/2005

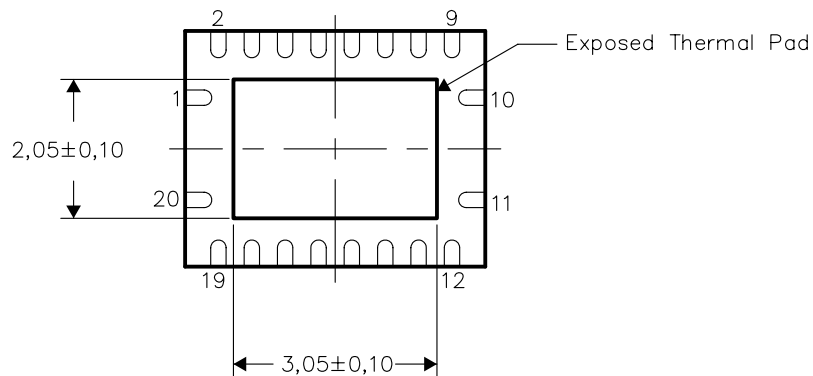
- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.
 - D** The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - E** Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
 - F. Package complies to JEDEC MO-241 variation BC.

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, Quad Flatpack No-Lead Logic Packages, Texas Instruments Literature No. SCBA017. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.

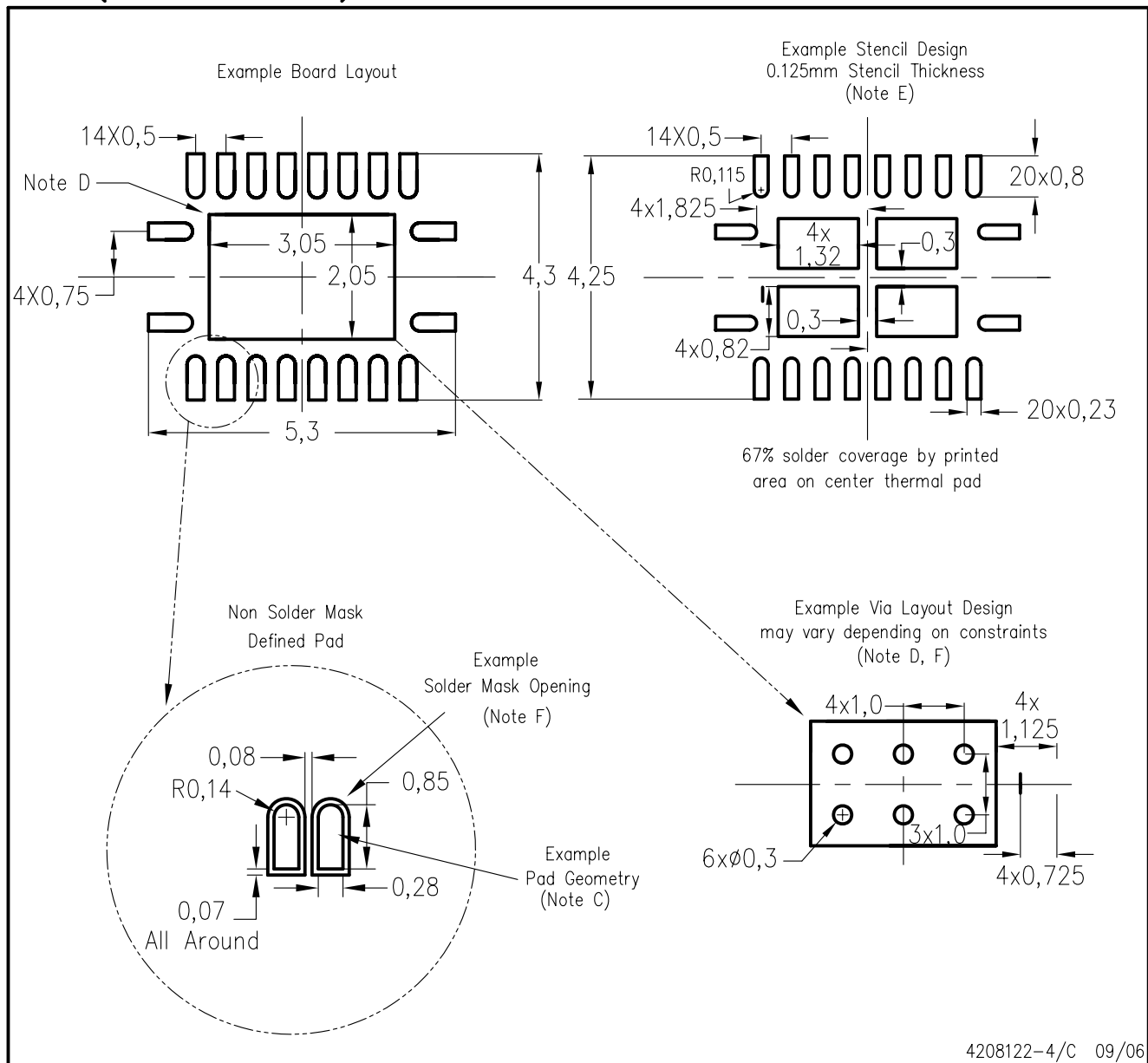


Bottom View

NOTE: All linear dimensions are in millimeters

Exposed Thermal Pad Dimensions

RGY (R-PQFP-N20)



4208122-4/C 09/06

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack Packages, Texas Instruments Literature No. SCBA017, SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AC.

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